



Material Content Data Sheet



Sales Product Name		TLE4274GS V25		Issued		28. August 2013		
MA#		MA000741326						
Package		PG-SOT223-4-21		Weight*		112.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.163	1.04	1.04	10376	10376
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		90	
	non noble metal	titanium	7440-32-6	0.051	0.05		453	
	non noble metal	chromium	7440-47-3	0.152	0.14		1358	
	non noble metal	copper	7440-50-8	50.489	45.06	45.26	450637	452538
wire	noble metal	gold	7440-57-5	0.117	0.10	0.10	1048	1048
encapsulation	organic material	carbon black	1333-86-4	0.461	0.41		4118	
	plastics	brominated resin	-	0.577	0.51		5148	
	inorganic material	antimonytrioxide	1309-64-4	1.154	1.03		10296	
	plastics	epoxy resin	-	10.497	9.37		93692	
	inorganic material	silicondioxide	60676-86-0	44.988	40.15	51.47	401539	514793
leadfinish	non noble metal	tin	7440-31-5	1.464	1.31	1.31	13067	13067
plating	noble metal	silver	7440-22-4	0.513	0.46	0.46	4579	4579
glue	plastics	epoxy resin	-	0.071	0.06		630	
	noble metal	silver	7440-22-4	0.333	0.30	0.36	2969	3599
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com